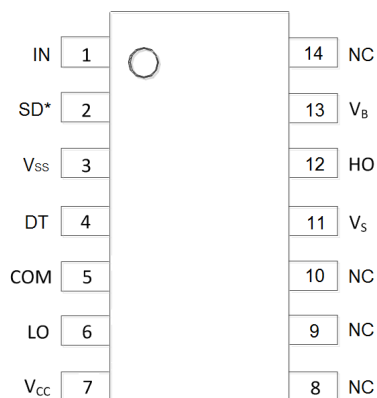


Pin Diagrams

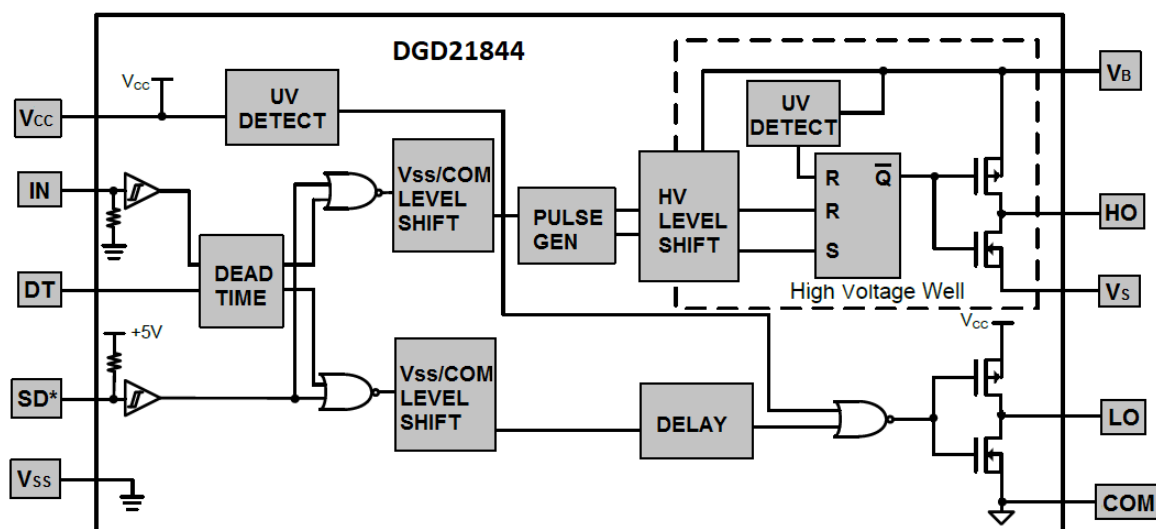


Top View SO-14

Pin Descriptions

Pin Number	Pin Name	Function
1	IN	Logic input for high-side and low-side gate driver outputs (HO and LO), in phase with HO (referenced to V _{SS})
2	SD*	Logic input for shutdown (referenced to V _{SS}), enabled low
3	V _{SS}	Logic ground
4	DT	Programmable Deadtime lead, referenced to V _{SS}
5	COM	Low-side return
6	LO	Low-side gate drive output
7	V _{CC}	Low-side and logic fixed supply
8,9,10,14	NC	No Connect (No Internal Connection)
11	V _S	High-side floating supply return
12	HO	High-side gate drive output
13	V _B	High-side floating supply

Functional Block Diagram



Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
High-Side Floating Supply Voltage	V _B	-0.3 to +624	V
High-Side Floating Supply Offset Voltage	V _S	V _B -24 to V _B +0.3	V
High-Side Floating Output Voltage	V _{HO}	V _S -0.3 to V _B +0.3	V
Offset Supply Voltage Transient	dV _S / dt	50	V/ns
Programmable Dead Time Pin Voltage	V _{DT}	V _{SS} -0.3 to V _{CC} +0.3	V
Logic and Low-Side Fixed Supply Voltage	V _{CC}	-0.3 to +24	V
Low-Side Output Voltage	V _{LO}	-0.3 to V _{CC} +0.3	V
Logic Supply Offset Voltage	V _{SS}	V _{CC} -24 to V _{CC} +0.3	V
Logic Input Voltage (IN and SD*)	V _{IN}	V _{SS} -0.3 to V _{CC} +0.3	V

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation Linear Derating Factor (Note 5)	P _D	1.0	W
Thermal Resistance, Junction to Ambient (Note 5)	R _{θJA}	120	°C/W
Operating Temperature	T _J	+150	°C
Lead Temperature (Soldering, 10s)	T _L	+300	
Storage Temperature Range	T _{STG}	-55 to +150	

Note: 5. When mounted on a standard JEDEC 2-layer FR-4 board.

Recommended Operating Conditions

Parameter	Symbol	Min	Max	Unit
High-Side Floating Supply Absolute Voltage	V _B	V _S + 10	V _S + 20	V
High-Side Floating Supply Offset Voltage	V _S	(Note 6)	600	V
High-Side Floating Output Voltage	V _{HO}	V _S	V _B	V
Logic and Low-Side Fixed Supply Voltage	V _{CC}	10	20	V
Low-Side Output Voltage	V _{LO}	0	V _{CC}	V
Logic Input Voltage (IN and SD*)	V _{IN}	V _{SS}	5	V
Programmable Dead Time Pin Voltage	V _{DT}	V _{SS}	V _{CC}	V
Logic Ground	V _{SS}	-5	5	V
Ambient Temperature	T _A	-40	+125	°C

Note: 6. Logic operation for V_S = -5V to +600V.

DC Electrical Characteristics (V_{BIAS} (V_{CC} , V_{BS}) = 15V, V_{SS} = COM, @ T_A = +25°C, unless otherwise specified.) (Note 7)

Parameter	Symbol	Min	Typ	Max	Unit	Conditions
Logic "1" Input Voltage for HO & Logic "0" for LO (Note 8)	V_{IH}	2.5	–	–	V	V_{CC} = 10V to 20V
Logic "0" Input Voltage for HO & Logic "1" for LO (Note 8)	V_{IL}	–	–	0.8	V	V_{CC} = 10V to 20V
SD* Input Positive Going Threshold	V_{SDTH+}	2.5	–	–	V	V_{CC} = 10V to 20V
SD* Input Negative Going Threshold	V_{SDTH-}	–	–	0.8	V	V_{CC} = 10V to 20V
High Level Output Voltage, $V_{BIAS} - V_O$	V_{OH}	–	–	1.4	V	I_O = 0mA
Low Level Output Voltage, V_O	V_{OL}	–	–	0.2	V	I_O = 20mA
Offset Supply Leakage Current	I_{LK}	–	–	50	μ A	$V_B = V_S = 600V$
Quiescent V_{BS} Supply Current	I_{BSQ}	20	60	150	μ A	$V_{IN} = 0V$ or 5V
Quiescent V_{CC} Supply Current	I_{CCQ}	0.4	1.0	1.8	mA	$V_{IN} = 0V$ or 5V
Logic "1" Input Bias Current	I_{IN+}	–	25	60	μ A	$I_N = 5V$, $SD^* = 0V$
Logic "0" Input Bias Current	I_{IN-}	–	–	1.0	μ A	$I_N = 0V$, $SD^* = 5V$
V_{BS} Supply Under-Voltage Positive Going Threshold	V_{BSUV+}	8.0	8.9	9.8	V	–
V_{BS} Supply Under-Voltage Negative Going Threshold	V_{BSUV-}	7.4	8.2	9.0	V	–
V_{CC} Supply Under-Voltage Positive Going Threshold	V_{CCUV+}	8.0	8.9	9.8	V	–
V_{CC} Supply Under-Voltage Negative Going Threshold	V_{CCUV-}	7.4	8.2	9.0	V	–
Output High Short Circuit Pulsed Current	I_{O+}	1.4	1.9	–	A	$V_O = 0V$, $PW \leq 10\mu s$
Output Low Short Circuit Pulsed Current	I_{O-}	1.7	2.3	–	A	$V_O = 15V$, $PW \leq 10\mu s$

Notes: 7. The V_{IN} and I_{IN} parameters are referenced to V_{SS} and are applicable to the two logic input pins: I_N and SD^* . The V_O and I_O parameters are referenced to COM and are applicable to the respective output pins: HO and LO.
 8. For optimal operation, it is recommended that the input pulses (I_N and SD^*) should have a minimum amplitude of 2.5V with a minimum pulse width of $2 \times \text{Deadtime}$ (t_{DT}).

AC Electrical Characteristics (V_{BIAS} (V_{CC} , V_{BS}) = 15V, V_{SS} = COM, C_L = 1000pF, @ T_A = +25°C, unless otherwise specified.)

Parameter	Symbol	Min	Typ	Max	Unit	Conditions
Turn-On Propagation Delay	t_{ON}	–	680	900	ns	$V_S = 0V$
Turn-Off Propagation Delay	t_{OFF}	–	270	400	ns	$V_S = 0V$ or 600V
Shut-Down Propagation Delay	t_{SD}	–	180	270	ns	–
Delay Matching, HO & LO Turn-On	t_{DMON}	–	–	90	ns	–
Delay Matching, HO & LO Turn-Off	t_{DMOFF}	–	–	40	ns	–
Turn-On Rise Time	t_R	–	40	60	ns	$V_S = 0V$
Turn-Off Fall Time	t_F	–	20	35	ns	$V_S = 0V$
Deadtime: $t_{DT\ LO-HO}$ & $t_{DT\ HO-LO}$	t_{DT}	280	400	520	ns	$R_{DT} = 0\Omega$
		4	5	6	μs	$R_{DT} = 200k\Omega$
Deatime Matching = $t_{DT\ LO-HO} - t_{DT\ HO-LO}$	t_{MDT}	–	0	50	ns	$R_{DT} = 0\Omega$
		–	0	600	ns	$R_{DT} = 200k\Omega$

Timing Waveforms

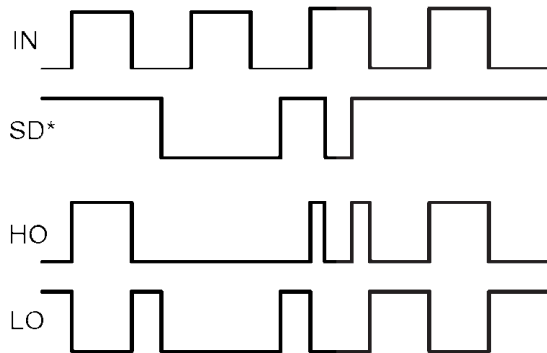


Figure 1. Input / Output Timing Diagram

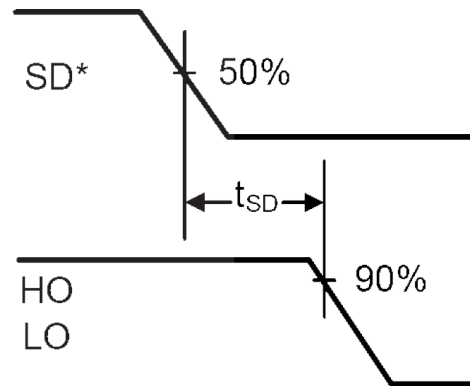
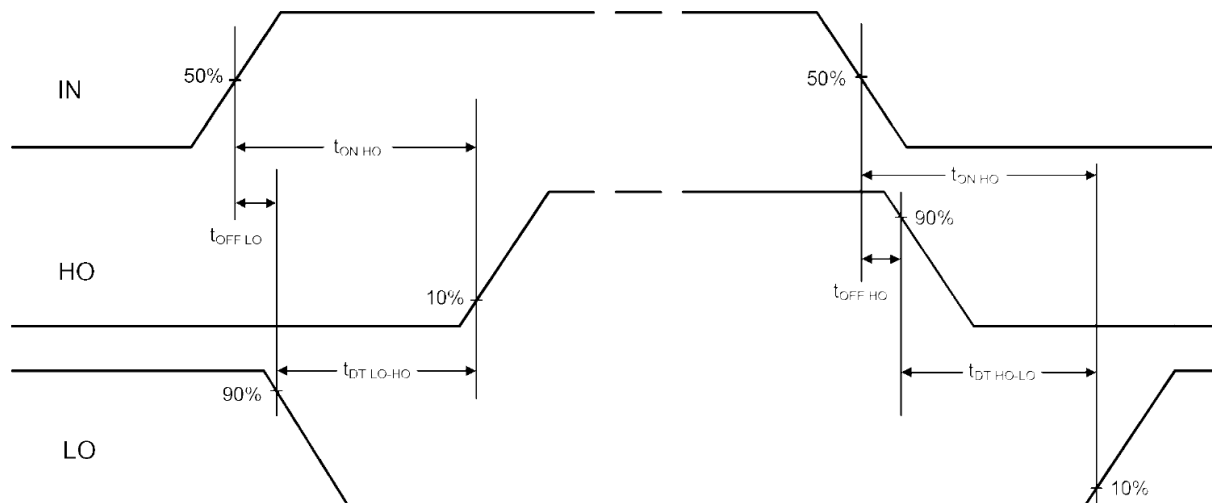


Figure 2. Shutdown Waveform Definitions



$$\text{Deadtime } t_{DT\ LO-HO} = t_{ON\ HO} - t_{OFF\ LO}$$

$$t_{DT\ HO-LO} = t_{ON\ LO} - t_{OFF\ HO}$$

Deadtime matching

$$t_{MDT} = t_{DT\ LO-HO} - t_{DT\ HO-LO}$$

Delay matching

$$t_{DM\ OFF} = t_{OFF\ LO} - t_{OFF\ HO}$$

Figure 3. Switching Time Waveform Definitions

Typical Performance Characteristics ($V_{CC}=15V$, $@T_A = +25^{\circ}C$, unless otherwise specified.)

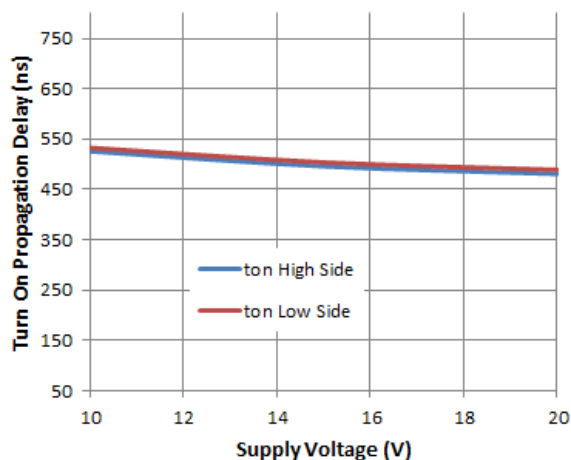


Figure 4. Turn-on Propagation Delay vs. Supply Voltage

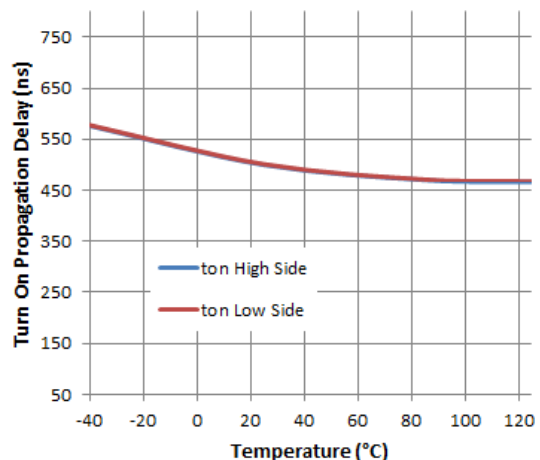


Figure 5. Turn-on Propagation Delay vs. Temperature

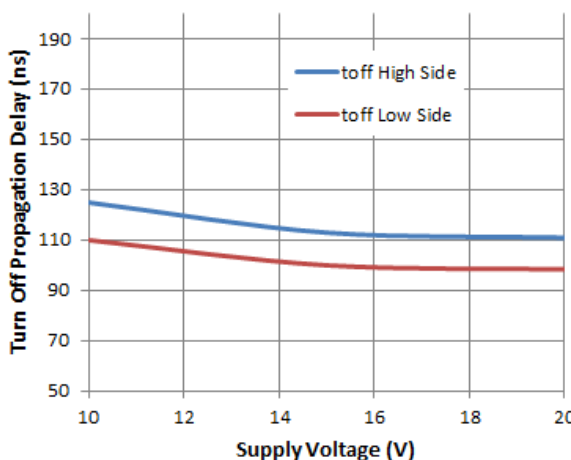


Figure 6. Turn-off Propagation Delay vs. Supply Voltage

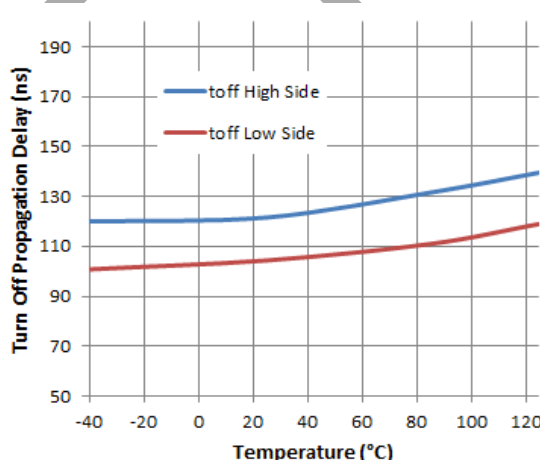


Figure 7. Turn-off Propagation Delay vs. Temperature

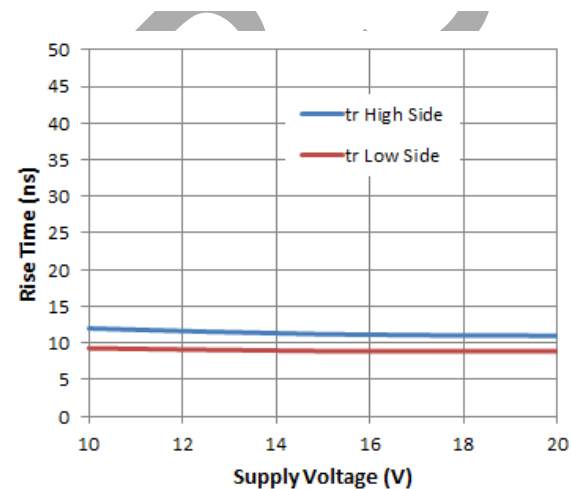


Figure 8. Rise Time vs. Supply Voltage

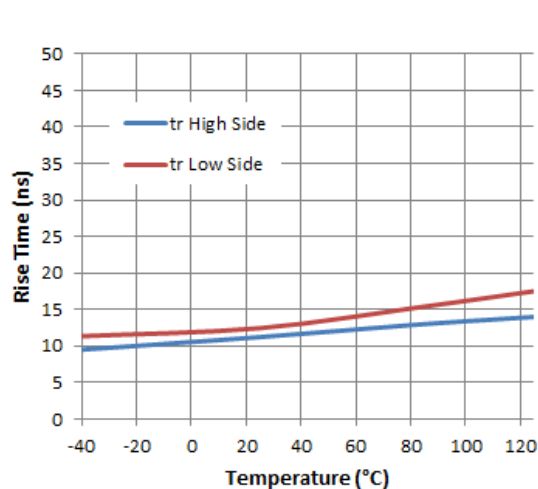


Figure 9. Rise Time vs. Temperature

Typical Performance Characteristics (continued)

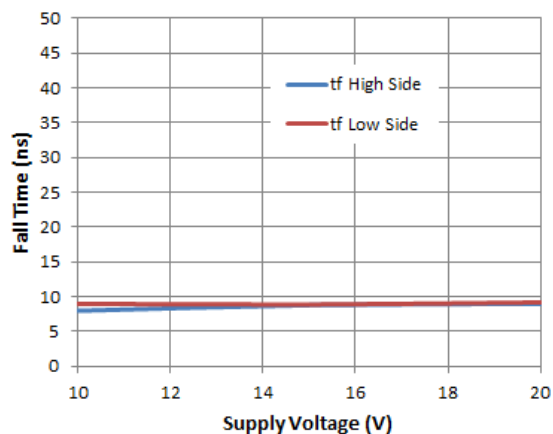


Figure 10. Fall Time vs. Supply Voltage

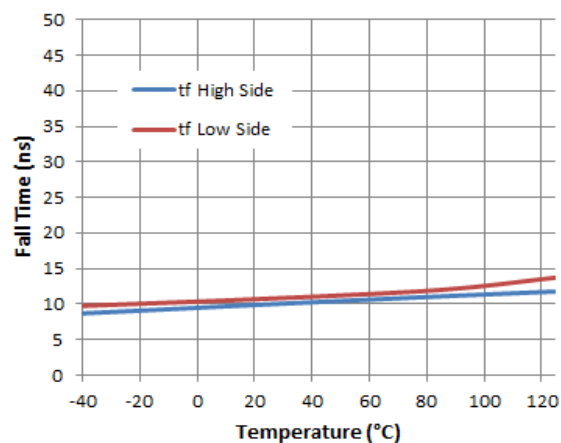


Figure 11. Fall Time vs. Temperature

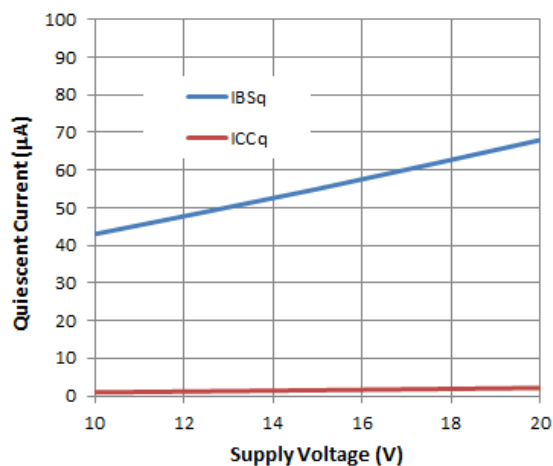


Figure 12. Quiescent Current vs. Supply Voltage

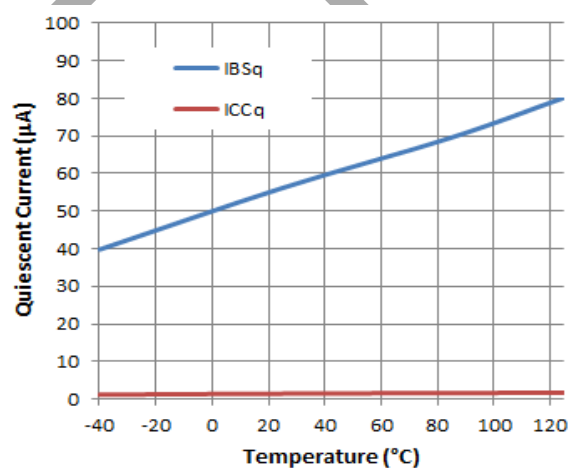


Figure 13. Quiescent Current vs. Temperature

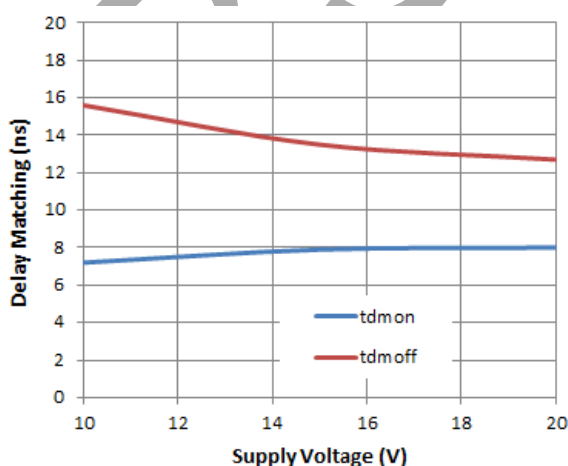


Figure 14. Delay Matching vs. Supply Voltage

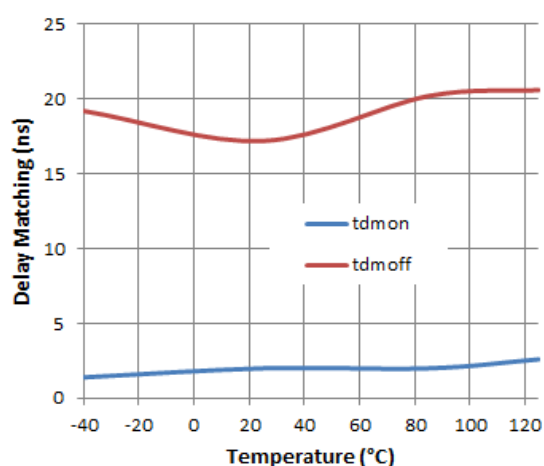


Figure 15. Delay Matching vs. Temperature

Typical Performance Characteristics (continued)

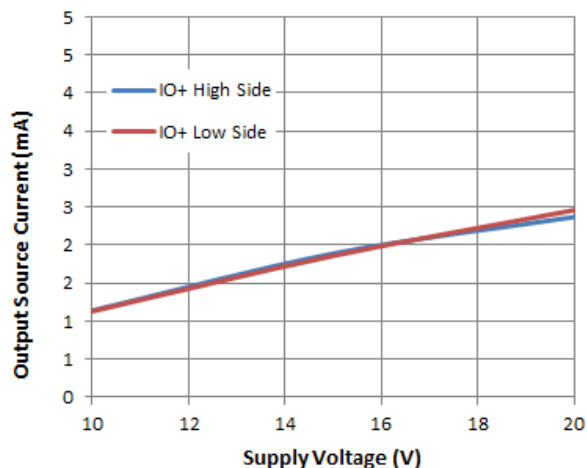


Figure 16. Output Source Current vs. Supply Voltage

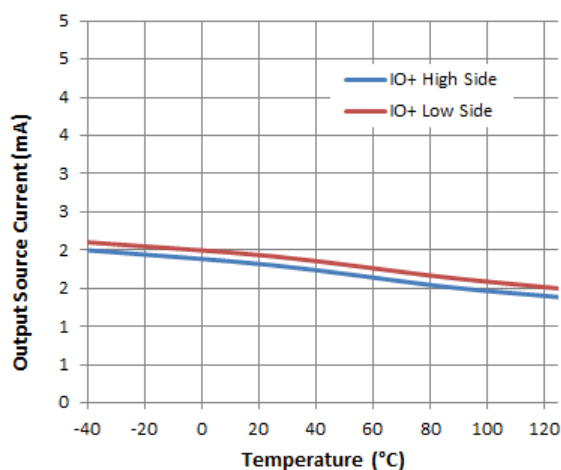


Figure 17. Output Source Current vs. Temperature

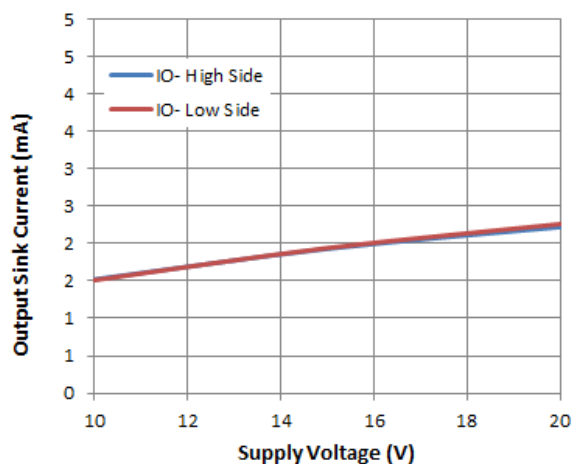


Figure 18. Output Sink Current vs. Supply Voltage

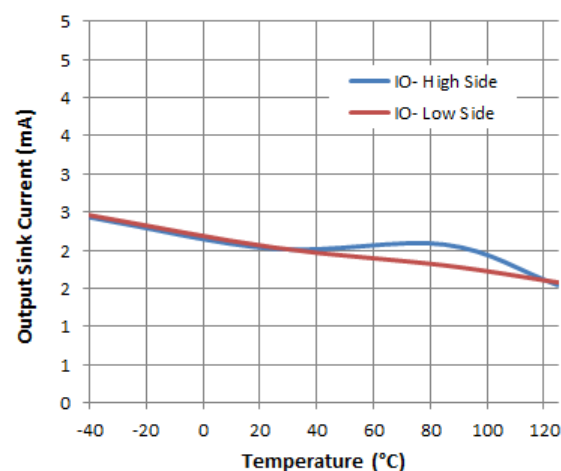


Figure 19. Output Sink Current vs. Temperature

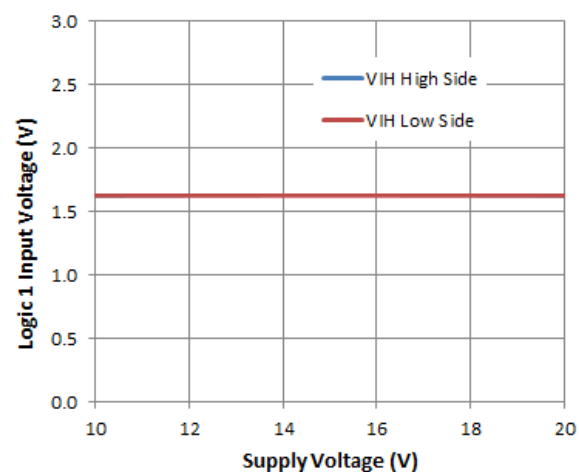


Figure 20. Logic 1 Input Voltage vs. Supply Voltage

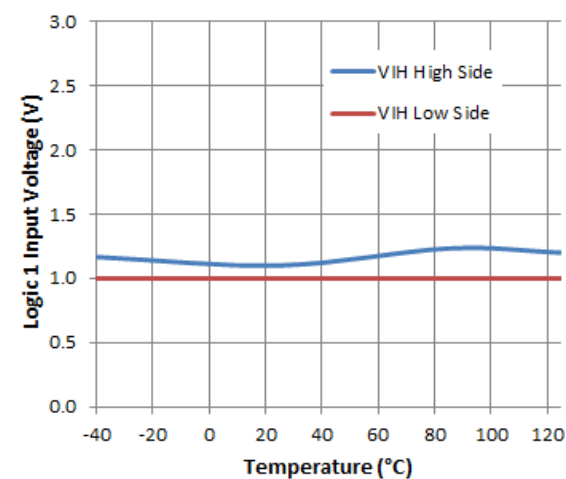


Figure 21. Logic 1 Input Voltage vs. Temperature

Typical Performance Characteristics (continued)

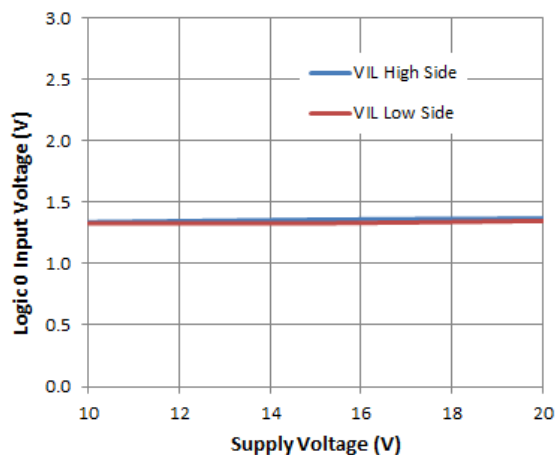


Figure 22. Logic 0 Input Voltage vs. Supply Voltage

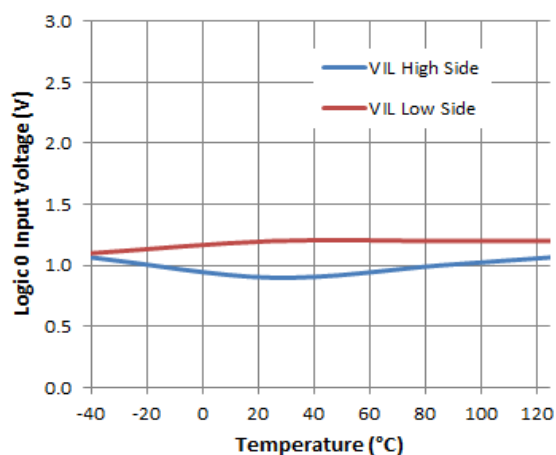


Figure 23. Logic 0 Input Voltage vs. Temperature

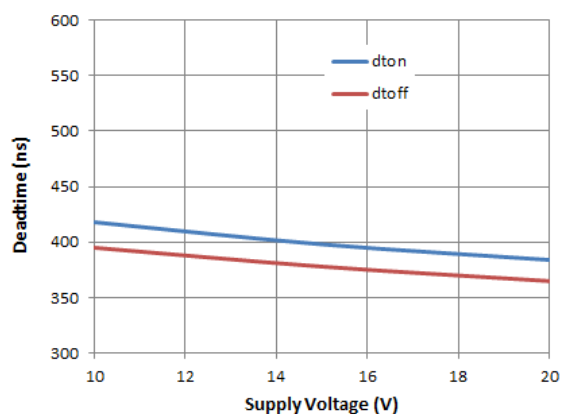


Figure 24. Deadtime vs. Supply Voltage

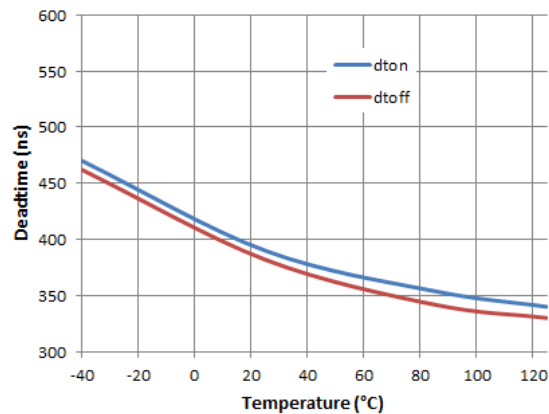


Figure 25. Deadtime vs. Temperature

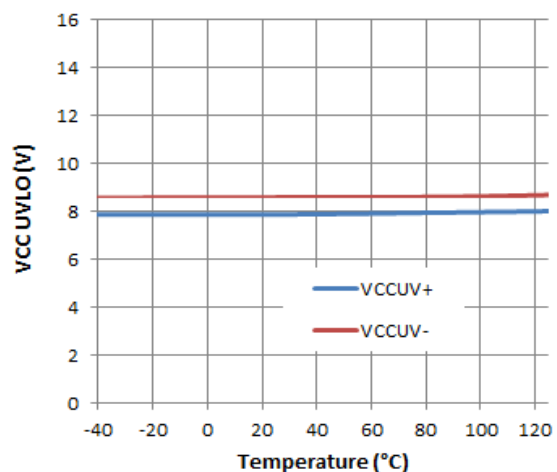


Figure 26. VCC UVLO vs. Temperature

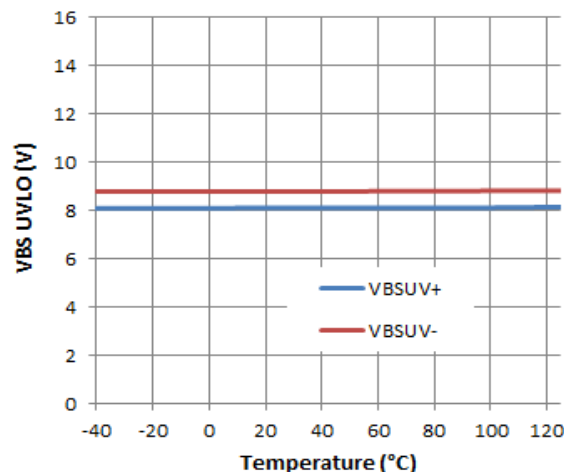


Figure 27. VBS UVLO vs. Temperature

Typical Performance Characteristics (continued)

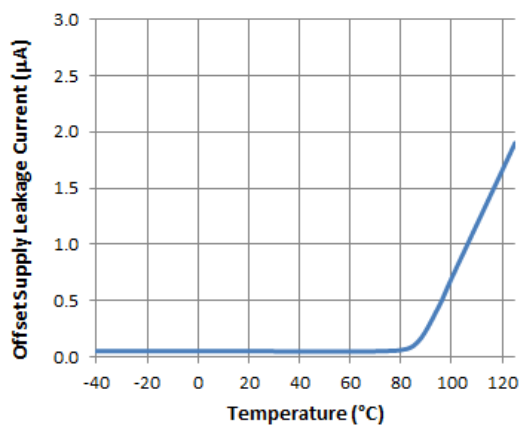


Figure 28. Offset Supply Leakage Current vs. Temperature

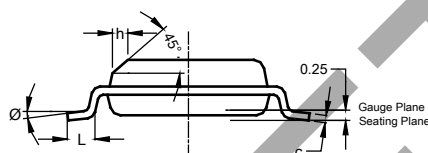
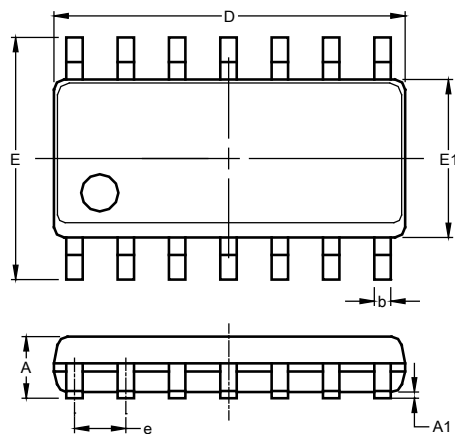
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OBsolete

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SO-14 (Type TH)

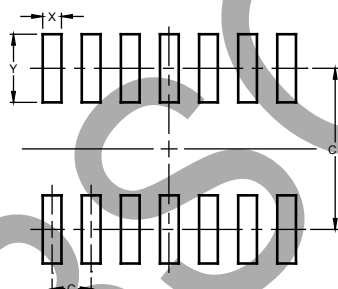


SO-14 (Type TH)			
Dim	Min	Max	Typ
A	1.55	1.73	--
A1	0.10	0.25	--
b	0.35	0.51	--
c	0.190	0.248	--
D	8.56	8.74	8.61
E	5.84	6.20	6.00
E1	3.81	3.99	3.94
e	--	--	1.27
h	--	--	0.33
L	0.41	0.89	--
Ø	0°	8°	--
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SO-14 (Type TH)



Dimensions	Value (in mm)
C	1.27
C1	5.20
X	0.60
Y	2.20

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.

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